



(51) International Patent Classification:

F24H 4/02 (2022.01) F24H 1/00 (2022.01)
F24D 12/00 (2006.01) F25D 31/00 (2006.01)
F24D 15/04 (2006.01) G06F 1/20 (2006.01)

(21) International Application Number:

PCT/CA2022/050406

(22) International Filing Date:

17 March 2022 (17.03.2022)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

3113022 23 March 2021 (23.03.2021) CA

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(81) Designated States (unless otherwise indicated, for every kind of national protection available):

AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DJ, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IR, IS, IT, JM, JO, JP, KE, KG, KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, WS, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available):

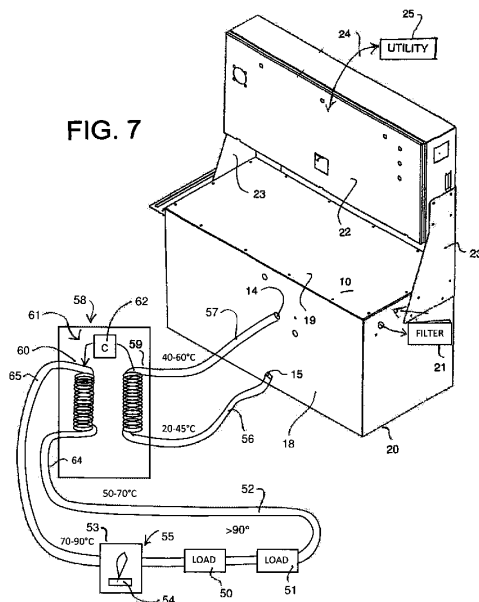
ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, ST, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG).

Published:

— with international search report (Art. 21(3))

(54) Title: HEATING SYSTEM USING HEAT EXTRACTED FROM A COMPUTER PROCESSING UNIT

FIG. 7



(57) Abstract: Computer processing systems are cooled and the otherwise wasted heat is extracted for space heating by providing a cooling dielectric liquid in a tank which passes from a manifold at the bottom of the tank through an array of tubular housings each having open top and bottom ends and containing row of the circuit boards. The housings sit on a divider sheet which has arrays of openings aligned with the housings allowing the liquid to pass from the manifold under little or no pressure so that the liquid flows through the housings by convection and stratifies to generate a layer of heated liquid above the open tops of the housings which can be tapped off to a heat exchanger. A heat pump acts on the cooling liquid to transfer heat to a heat transfer liquid which can be further heated by a boiler and transferred to existing heat dissipating loads.